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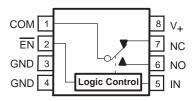
Description

The TS5A2053 is a single-pole double-throw (SPDT) analog switch that is designed to operate from 1.65 V to 5.5 V. This device can handle both digital and analog signals, and signals up to V_{+} can be transmitted in either direction.

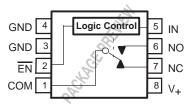
Applications

- Cell Phones
- Portable Audio Video Equipment
- Battery-Powered Equipment
- Low-Voltage Data-Acquisition Systems
- Test Equipment
- Communication Circuits

SSOP OR VSSOP PACKAGE (TOP VIEW)



YEP OR YZP PACKAGE (BOTTOM VIEW)



FUNCTION TABLE

EN	IN	NC TO COM, COM TO NC	NO TO COM, COM TO NO
L	L	ON	OFF
L	Н	OFF	ON
Н	Х	OFF	OFF

Features

- Low ON-State Resistance (10 Ω)
- Control Inputs Are 5-V Tolerant
- Low Charge Injection
- Excellent ON-Resistance Matching
- Low Total Harmonic Distortion (THD)
- 1.65-V to 5.5-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)

Summary of Characteristics

 $V_{+} = 5 \text{ V} \text{ and } T_{A} = 25 ^{\circ}\text{C}$

Configuration	Single Pole Double Throw (SPDT)
Number of channels	1
ON-state resistance (ron)	7.5 Ω
ON-state resistance match (Δr _{on})	0.8 Ω
ON-state resistance flatness (ron(flat))	1.7 Ω
Turn-on/turn-off time (tON/tOFF)	6.8 ns/4.1 ns
Charge injection (Q _C)	3 pC
Bandwidth (BW)	330 MHz
OFF isolation (OISO)	-64 dB at 10 MHz
Crosstalk (XTALK)	-68 dB at 10 MHz
Total harmonic distortion (THD)	0.01%
Leakage current (ICOM(OFF))	±10 nA
Power-supply current (I+)	0.1 μΑ
Package options	8-pin DSBGA, SSOP, or VSSOP



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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ORDERING INFORMATION

TA	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP	Townson	TS5A2053YEPR	
-40°C to 85°C	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Tape and reel	TS5A2053YZPR	
	SSOP - DCT	Tape and reel	TS5A2053DCTR	JAF
	VSSOP - DCU	Tape and reel	TS5A2053DCUR	JAF_

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Absolute Minimum and Maximum Ratings(1)(2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
٧+	Supply voltage range(3)		-0.5	6.5	V
V _{NO} V _{NC} V _{COM}	Analog voltage range(3)(4)(5)		-0.5	V ₊ + 0.5	V
lΚ	Analog port diode current	V_{NC} , V_{NO} , $V_{COM} < 0$ or V_{NO} , V_{NC} , $V_{COM} > V_{+}$	-50	50	mA
INO INC ICOM	On-state switch current	V_{NC} , V_{NO} , $V_{COM} = 0$ to V_{+}	-50	50	mA
VI	Digital input voltage range(3)(4)		-0.5	6.5	V
lıK	Digital input clamp current	V _I < 0	-50		mA
I ₊	Continuous current through V+			100	mA
IGND	Continuous current through GND		-100		mA
		DCT package		220	
θJΑ	Package thermal impedance(6)	DCU package		227	°C/W
		YEP/YZP package		102	
T _{stg}	Storage temperature range		-65	150	°C

⁽¹⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

⁽²⁾ DCT. The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.

DCU: The actual top-side marking has one additional character that designates the assembly/test site.

YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, \bullet = Pb-free).

⁽²⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

⁽³⁾ All voltages are with respect to ground, unless otherwise specified.

⁽⁴⁾ The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

⁽⁵⁾ This value is limited to 5.5 V maximum.

⁽⁶⁾ The package thermal impedance is calculated in accordance with JESD 51-7.



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Electrical Characteristics for 5-V Supply⁽¹⁾ $V_+ = 4.5 \text{ V}$ to 5.5 V, $T_A = -40^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITI	ONS	TA	٧+	MIN	TYP	MAX	UNIT
Analog Switch	•				•				
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		٧+	V
ON-state resistance	-	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$	Switch ON,	25°C	4.5 V		7.5	13.8	Ω
ON-State resistance	r _{on}	$I_{COM} = -32 \text{ mA},$	See Figure 13	Full	4.5 V			16	52
ON-state resistance		V_{NO} or $V_{NC} = 3.15 \text{ V}$,	Switch ON,	25°C			0.8		_
match between channels	$\Delta r_{\sf on}$	$I_{COM} = -32 \text{ mA},$	See Figure 13	Full	4.5 V			4.5	Ω
ON-state resistance		$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$	Switch ON,	25°C	451/		1.7		0
flatness	ron(flat)	$I_{COM} = -32 \text{ mA},$	See Figure 13	Full	4.5 V			4.5	Ω
NO, NC	I _{NO(OFF)} ,	V _{NO} or V _{NC} = 1 V, V _{COM} = 4.5 V,	Switch OFF,	25°C		-100	5	100	
OFF leakage current	INC(OFF)	or V _{NO} or V _{NC} = 4.5 V, V _{COM} = 1 V,	See Figure 14	Full	5.5 V	-200		200	nA
СОМ		V _{COM} = 1 V, V _{NO} or V _{NC} = 4.5 V,	Switch OFF,	25°C	5.5.1/	-100	-1	100	- A
OFF leakage current	ICOM(OFF)	or V _{COM} = 4.5 V, V _{NO} or V _{NC} = 1 V,	See Figure 14	Full	5.5 V	-200		200	nA
NO, NC	I _{NO(ON),}	V _{NO} = 1 V, V _{COM} = Open,	Switch ON,	25°C		-100	5.5	100	
ON leakage current	INC(ON)	or V _{NO} = 4.5 V, V _{COM} = Open,	See Figure 15	Full	5.5 V	-200		200	nA
СОМ		V _{COM} = 1 V, V _{NO} or V _{NC} = Open,	Switch ON,	25°C	551/	-100	-1	100	
ON leakage current	ICOM(ON)	or V _{COM} = 4.5 V, V _{NO} or V _{NC} = Open,	See Figure 15	Full 5	5.5 V	-200		200	nA
Digital Control Input	s (IN, EN)				_	_			
Input logic high	VIH			Full		V ₊ × 0.7		5.5	V
Input logic low	V _{IL}			Full		0		$V_{+} \times 0.3$	V
Input leakage	lu e lu	V ₁ = 5.5 V ₁ or 0		25°C	551/	-0.1	0.05	0.1	^
current	¹IH, ¹IL	$V_{I} = 5.5 \text{ V or } 0$		Full	5.5 V	-1		1	μΑ

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



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Electrical Characteristics for 5-V Supply⁽¹⁾ (continued) $V_+ = 4.5 \text{ V to } 5.5 \text{ V}, T_A = -40 ^{\circ}\text{C to } 85 ^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST COND	DITIONS	TA	V ₊	MIN	TYP	MAX	UNIT
Dynamic	•								
Turn-on time	4	V _{COM} = 3 V,	C _L = 35 pF,	25°C	5 V	3.8	5.3	6.8	20
Turr-on time	tON	$R_L = 300 \Omega$,	See Figure 17	Full	4.5 V to 5.5 V	3		7.1	ns
Turn-off time	tOFF	V _{COM} = 3 V,	$C_L = 35 \text{ pF},$	25°C	5 V	0.8	1.9	4.1	ns
	OFF	$R_L = 300 \Omega$	See Figure 17	Full	4.5 V to 5.5 V	0.4		4.5	110
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	C _L = 0.1 nF, See Figure 21	25°C	5 V		3		рС
NO, NC OFF capacitance	C _{NO(OFF)} , C _{NC(OFF)}	V_{NO} or $V_{NC} = V_{+}$ or GND, Switch OFF,	See Figure 16	25°C	5 V		6		pF
COM OFF capacitance	CCOM(OFF)	V _{COM} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	5 V		9.5		pF
NO, NC ON capacitance	C _{NO(ON)} , C _{NC(ON)}	V_{NO} or $V_{NC} = V_{+}$ or GND, Switch ON,	See Figure 16	25°C	5 V		18		pF
COM ON capacitance	C _{COM(ON)}	V _{COM} = V ₊ or GND, Switch ON,	See Figure 16	25°C	5 V		18		pF
Digital input capacitance	Cl	$V_I = V_+ \text{ or GND},$	See Figure 16	25°C	5 V		2.5		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 18	25°C	5 V		330		MHz
OFF isolation	O _{ISO}	$R_L = 50 \Omega$, f = 10 MHz,	Switch OFF, See Figure 19	25°C	5 V		-64		dB
Crosstalk	X _{TALK}	$R_L = 50 \Omega$, f = 10 MHz,	Switch ON, See Figure 20	25°C	5 V		-68		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 22	25°C	5 V		0.01		%
Supply				•					
Positive supply current	1+	$V_I = V_+$ or GND,	Switch ON or OFF	25°C Full	5.5 V		0.1	1 5	μА

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



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Electrical Characteristics for 3.3-V Supply⁽¹⁾ $V_+ = 3 \text{ V to } 3.6 \text{ V}, T_A = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C} \text{ (unless otherwise noted)}$

PARAMETER	SYMBOL	TEST CONDITIONS	3	TA	٧+	MIN	TYP	MAX	UNIT
Analog Switch				•					
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V ₊	٧
ON-state resistance	r _{on}	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -24 \text{ mA},$	Switch ON, See Figure 13	25°C Full	3 V		13.2	20	Ω
ON-state resistance match	Δr _{on}	V_{NO} or $V_{NC} = 2.1 \text{ V}$,	Switch ON,	25°C	3 V		1		Ω
between channels	011	$I_{COM} = -24 \text{ mA},$	See Figure 13	Full				5.5	
ON-state resistance flatness	ron(flat)	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -24 \text{ mA},$	Switch ON, See Figure 13	25°C Full	3 V		5.3	11	Ω
NO, NC	INO(OFF),	V_{NO} or $V_{NC} = 1$ V, $V_{COM} = 3$ V,	Switch OFF.	25°C		-100	4	100	
OFF leakage current	INC(OFF)	or V_{NO} or $V_{NC} = 3 \text{ V}$, $V_{COM} = 1 \text{ V}$,	See Figure 14	Full	3.6 V	-200		200	nA
COM		$V_{COM} = 1 \text{ V}, V_{NO} \text{ or } V_{NC} = 3 \text{ V},$	Switch OFF,	25°C	0.01/	-100	-1	100	
OFF leakage current	COM(OFF)	$V_{COM} = 3 \text{ V}, V_{NO} \text{ or } V_{NC} = 1 \text{ V},$	See Figure 14	Full	3.6 V	-200		200	nA
NO, NC	INO(ON),	V_{NO} or $V_{NC} = 1$ V, $V_{COM} = Open$,	Switch ON,	25°C	261/	-100	4.5	100	~ A
ON leakage current	INC(ON)	V_{NO} or $V_{NC} = 3 V$, $V_{COM} = Open$,	See Figure 15	Full	3.6 V	-200		200	nA
COM		$V_{COM} = 1 V$, V_{NO} or $V_{NC} = Open$,	Switch ON,	25°C	0.01/	-100	-1	100	4
ON leakage current	ICOM(ON)	$V_{COM} = 3 \text{ V}, V_{NO} \text{ or } V_{NC} = \text{Open},$	See Figure 15	Full	3.6 V	-200		200	nA
Digital Control Inpu	ts (IN, EN)								
Input logic high	VIH			Full		V ₊ × 0.7		5.5	V
Input logic low	V _{IL}			Full		0		$V_{+} \times 0.3$	V
Input leakage current	I _{IH} , I _{IL}	V _I = 5.5 V or 0		25°C Full	3.6 V	-0.1 -1	0.05	0.1	μΑ

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



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Electrical Characteristics for 3.3-V Supply⁽¹⁾ (continued) $V_+ = 3 \text{ V to } 3.6 \text{ V}, T_A = -40^{\circ}\text{C to}$ 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST COND	OITIONS	TA	٧+	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time	tON	V _{COM} = 2 V,	C _L = 35 pF,	25°C	3.3 V	5	6.4	7.9	ns
	*ON	$R_L = 300 \Omega$	See Figure 17	Full	3 V to 3.6 V	4.5		8.2	110
Turn-off time	torr	$V_{COM} = 2 V$	$C_L = 35 pF$,	25°C	3.3 V	1.1	2.4	4.7	ns
Tarri on timo	tOFF	$R_L = 300 \Omega$,	See Figure 17	Full	3 V to 3.6 V	0.3		5	113
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0,	$C_L = 0.1 \text{ nF},$ See Figure 21	25°C	3.3 V		1		рС
NO, NC OFF capacitance	C _{NO(OFF)}	V_{NO} or $V_{NC} = V_{+}$ or GND, Switch OFF,	See Figure 16	25°C	3.3 V		6		pF
COM OFF capacitance	CCOM(OFF)	V _{COM} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	3.3 V		9.5		pF
NO, NC ON capacitance	C _{NO(ON)}	V_{NO} or $V_{NC} = V_{+}$ or GND, Switch ON,	See Figure 16	25°C	3.3 V		18.5		pF
COM ON capacitance	C _{COM(ON)}	V _{COM} = V ₊ or GND, Switch ON,	See Figure 16	25°C	3.3 V		18.5		pF
Digital input capacitance	Cl	$V_I = V_+ \text{ or GND},$	See Figure 16	25°C	3.3 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 18	25°C	3.3 V		320		MHz
OFF isolation	O _{ISO}	$R_L = 50 \Omega$, f = 10 MHz,	Switch OFF, See Figure 19	25°C	3.3 V		-64		dB
Crosstalk	XTALK	$R_L = 50 \Omega$, f = 10 MHz,	Switch ON, See Figure 20	25 °C	3.3 V		-68		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 22	25°C	3.3 V		0.035		%
Supply	•								
Positive supply current	I ₊	$V_I = V_+ \text{ or GND},$	Switch ON or OFF	25°C Full	3.6 V		0.1	1 5	μΑ

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Electrical Characteristics for 2.5-V Supply⁽¹⁾ $V_+ = 2.3 \text{ V to } 2.7 \text{ V, T}_A = -40 ^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDIT	IONS	TA	٧+	MIN	TYP	MAX	UNIT
Analog Switch	1								
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V ₊	V
ON-state resistance	r _{on}	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	25°C Full	2.3 V		20	40	Ω
ON-state resistance match between channels	Δr _{on}	V_{NO} or $V_{NC} = 1.6 \text{ V}$, $I_{COM} = -8 \text{ mA}$,	Switch ON, See Figure 13	25°C Full	2.3 V		1.1	6	Ω
ON-state resistance flatness	ron(flat)	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 13	25°C Full	2.3 V		15	20	Ω
NO, NC	INO(OFF),	V _{NO} or V _{NC} = 0.5 V, V _{COM} = 2.2 V,	Switch OFF,	25°C	0.7.1/	-100	3.5	100	^
OFF leakage current	INC(OFF)	or V _{NO} or V _{NC} = 2.2 V, V _{COM} = 0.5 V,	See Figure 14	Full	2.7 V	-200		200	nA
COM	lagruage	V _{COM} = 0.5 V, V _{NO} or V _{NC} = 2.2 V, or	Switch OFF,	25°C	2.7 V	-100	-2	100	nA
OFF leakage current	ICOM(OFF)	V _{COM} = 2.2 V, V _{NO} or V _{NC} = 0.5 V,	See Figure 14	Full	Z.1 V	-200		200	IIA
NO, NC	I _{NO(ON),}	V_{NO} or $V_{NC} = 0.5 V$, $V_{COM} = Open$,	Switch ON,	25°C	2.7 V	-100	4	100	nA
ON leakage current	INC(ON)	V _{NO} or V _{NC} = 2.2 V, V _{COM} = Open,	See Figure 15	Full	Z.1 V	-200		200	
COM	loo. wo. v	V _{COM} = 0.5 V, V _{NO} or V _{NC} = Open, or	Switch ON,	25°C	2.7 V	-100	-2	100	nA
ON leakage current	ICOM(ON)	V _{COM} = 2.2 V, V _{NO} or V _{NC} = Open,	See Figure 15	Full	2.7 V	-200		200	nA
Digital Control Input	s (IN, EN)								
Input logic high	VIH			Full		V ₊ ×0.7		5.5	V
Input logic low	V _{IL}			Full		0		$V_{+} \times 0.3$	V
Input leakage current	I _{IH} , I _{IL}	V _I = 5.5 V or 0		25°C Full	2.7 V	-0.1 -1	0.05	0.1	μА

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



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Electrical Characteristics for 2.5-V Supply⁽¹⁾ (continued) $V_+ = 2.3 \text{ V to } 2.7 \text{ V}, T_A = -40 ^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDI	ITIONS	TA	V ₊	MIN	TYP	MAX	UNIT
Dynamic	•								
Turn-on time		V _{COM} = 1.5 V,	C _L = 35 pF,	25°C	2.5 V	5.9	7.1	9.3	
rum-on ume	tON	$R_L = 300 \Omega$,	See Figure 17	Full	2.3 V to 2.7 V	5.1		10	ns
Turn-off time	torr	V _{COM} = 1.5 V,	$C_L = 35 pF$,	25°C	2.5 V	2.1	3.2	5.1	ns
	tOFF	$R_L = 300 \Omega$,	See Figure 17	Full	2.3 V to 2.7 V	1.2		5.2	113
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0	C _L = 0.1 nF, See Figure 21	25°C	2.5 V		0.5		рC
NO, NC OFF capacitance	C _{NO(OFF)} C _{NC(OFF)}	V_{NO} or $V_{NC} = V_{+}$ or GND, Switch OFF,	See Figure 16	25°C	2.5 V		6.5		pF
COM OFF capacitance	CCOM(OFF)	V _{COM} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	2.5 V		10		pF
NO, NC ON capacitance	C _{NO(ON)}	V_{NO} or $V_{NC} = V_{+}$ or GND, Switch ON,	See Figure 16	25°C	2.5 V		18.5		pF
COM ON capacitance	C _{COM(ON)}	V _{COM} = V ₊ or GND, Switch ON,	See Figure 16	25°C	2.5 V		18.5		pF
Digital input capacitance	Cl	$V_I = V_+$ or GND,	See Figure 16	25°C	2.5 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 18	25°C	2.5 V		320		MHz
OFF isolation	O _{ISO}	$R_L = 50 \Omega$, f = 10 MHz,	Switch OFF, See Figure 19	25°C	2.5 V		-64		dB
Crosstalk	XTALK	$R_L = 50 \Omega$, f = 10 MHz,	Switch ON, See Figure 20	25 °C	2.5 V		-68		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 22	25°C	2.5 V		0.26		%
Supply									
Positive supply current	I ₊	$V_I = V_+$ or GND,	Switch ON or OFF	25°C Full	2.7 V		0.1	1 5	μΑ

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



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Electrical Characteristics for 1.8-V Supply⁽¹⁾ $V_+ = 1.65 \text{ V}$ to 1.95 V, $T_A = -40 ^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIO	NS	T_{A}	٧+	MIN	TYP	MAX	UNIT
Analog Switch					•				
Analog signal range	VCOM, VNO, VNC					0		٧+	V
ON-state resistance	r _{on}	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -4 \text{ mA},$	Switch ON, See Figure 13	25°C Full	1.65 V		85	120	Ω
ON-state resistance match	Δr _{on}	V _{NO} or V _{NC} = 1.15 V, I _{COM} = -4 mA,	Switch ON, See Figure 13	25°C	1.65 V		2		Ω
between channels				Full			70	7.5	
ON-state resistance flatness	ron(flat)	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -4 \text{ mA},$	Switch ON, See Figure 13	25°C Full	1.65 V		76	100	Ω
NO, NC	INO(OFF),	V _{NO} or V _{NC} = 0.3 V, V _{COM} = 1.65 V,	Switch OFF,	25°C	4.05.1/	-100	3.5	100	
OFF leakage current	INC(OFF)	or V _{NO} or V _{NC} = 1.65 V, V _{COM} = 0.3 V,	See Figure 14	Full	1.95 V	-200		200	nA
COM		$V_{COM} = 0.3 \text{ V}, V_{NO} = 1.65 \text{ V},$	Switch OFF,	25°C		-100	1	100	
OFF leakage current	ICOM(OFF)	$V_{COM} = 1.65 \text{ V}, V_{NO} = 0.3 \text{ V},$	See Figure 14	Full	1.95 V	-200		200	nA
NO, NC	I _{NO(ON),}	V _{NO} or V _{NC} = 0.3 V, V _{COM} = Open, or	Switch ON,	25°C	1.95 V	-100	4	100	nA
ON leakage current	INC(ON)	V _{NO} or V _{NC} = 1.65 V, V _{COM} = Open,	See Figure 15	Full	1.95 V	-200		200	
СОМ		$V_{COM} = 0.3 \text{ V},$ $V_{NO} \text{ or } V_{NC} = \text{Open},$	Switch ON,	25°C	4.05.1/	-100	1	100	^
ON leakage current	ICOM(ON)	or V _{COM} = 1.65 V, V _{NO} or V _{NC} = Open,	See Figure 15	Full	1.95 V	-200		200	nA
Digital Control Input	ts (IN, EN)								
Input logic high	VIH			Full		V ₊ × 0.65		5.5	V
Input logic low	VIL			Full		0		$V_{+} \times 0.35$	V
Input leakage current	I _{IH} , I _{IL}	V _I = 5.5 V or 0		25°C Full	1.95 V	-0.1 -1	0.05	0.1	μА

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



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Electrical Characteristics for 1.8-V Supply⁽¹⁾ (continued) $V_+ = 1.65 \text{ V}$ to 1.95 V, $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST COND	DITIONS	TA	V ₊	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time	ton	V _{COM} = 1.3 V,	C _L = 35 pF,	25°C	1.8 V	10.2	11.8	14.5	ns
Turr on time	tON	$R_L = 300 \Omega$,	See Figure 17	Full	1.65 V to 1.95 V	8.4		15.5	115
Turn-off time	tOFF	V _{COM} = 1.3 V,	C _L = 35 pF,	25°C	1.8 V	2.9	4.3	6.5	ns
Tarri on arrio	OFF	$R_L = 300 \Omega$	See Figure 17	Full	1.65 V to 1.95 V	2.2		7	113
Charge injection	QC	V _{GEN} = 0, R _{GEN} = 0	C _L = 0.1 nF, See Figure 21	25°C	1.8 V		0.5		рС
NO, NC OFF capacitance	C _{NO(OFF)} , C _{NC(OFF)}	V_{NO} or $V_{NC} = V_{+}$ or GND, Switch OFF,	See Figure 16	25°C	1.8 V		6.5		pF
COM OFF capacitance	CCOM(OFF)	V _{COM} = V ₊ or GND, Switch OFF,	See Figure 16	25°C	1.8 V		10		pF
NO, NC ON capacitance	C _{NO(ON)} , C _{NC(ON)}	V_{NO} or $V_{NC} = V_{+}$ or GND, Switch ON,	See Figure 16	25°C	1.8 V		19		pF
COM ON capacitance	C _{COM(ON)}	V _{COM} = V ₊ or GND, Switch ON,	See Figure 16	25°C	1.8 V		14		pF
Digital input capacitance	Cl	$V_I = V_+$ or GND,	See Figure 16	25°C	1.8 V		3		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 18	25°C	1.8 V		320		MHz
OFF isolation	O _{ISO}	$R_L = 50 \Omega$, $f = 10 MHz$,	Switch OFF, See Figure 19	25°C	1.8 V		-64		dB
Crosstalk	X _{TALK}	$R_L = 50 \Omega$, f = 10 MHz,	Switch ON, See Figure 20	25 °C	1.8 V		-68		dB
Total harmonic distortion	THD	$R_L = 10 \text{ k}\Omega,$ $C_L = 50 \text{ pF},$	f = 20 Hz to 20 kHz, See Figure 22	25°C	1.8 V		2.6		%
Supply	•								
Positive supply	I ₊	$V_1 = V_+$ or GND.	Switch ON or OFF	25°C	1.95 V		0.1	1	μА

⁽¹⁾ The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

TYPICAL PERFORMANCE

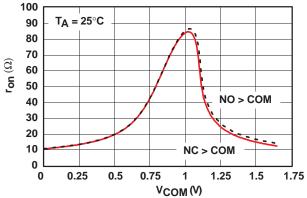


Figure 1A. r_{on} vs V_{COM} ($V_{+} = 1.65 \text{ V}$)

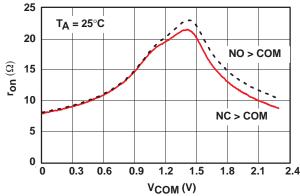


Figure 1B. r_{on} vs V_{COM} ($V_{+} = 2.3 \text{ V}$)

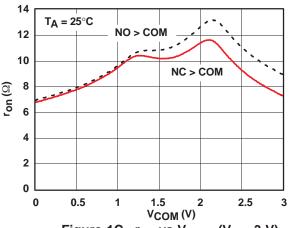


Figure 1C. r_{on} vs V_{COM} ($V_{+} = 3 V$)

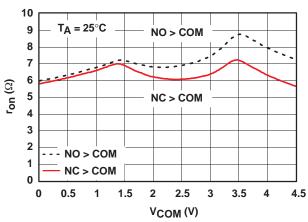


Figure 1D. r_{on} vs V_{COM} ($V_{+} = 4.5 \text{ V}$)

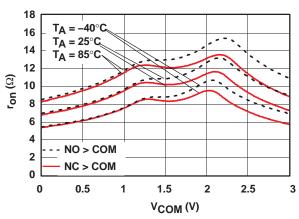


Figure 2. r_{on} vs V_{COM} ($V_{+} = 3$ V)

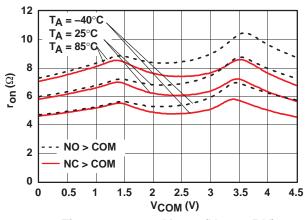


Figure 3. r_{on} vs V_{COM} ($V_{+} = 4.5 \text{ V}$)



TYPICAL PERFORMANCE (continued)

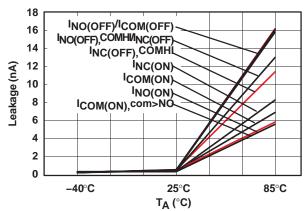


Figure 4. Leakage Current vs Temperature $(V_+ = 5.5 \text{ V})$

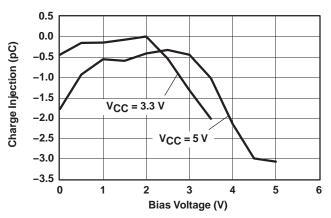


Figure 5. Charge Injection (Q_C) vs V_{COM}

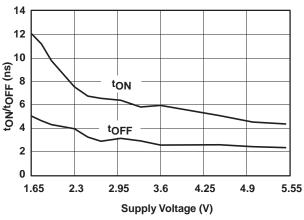


Figure 6. toN and toFF vs V+

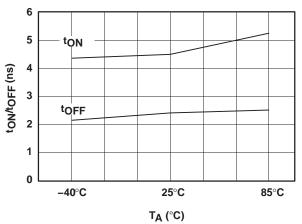


Figure 7. t_{ON} and t_{OFF} vs Temperature (V₊ = 5 V)

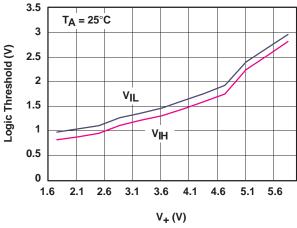


Figure 8. Logic Threshold vs V₊

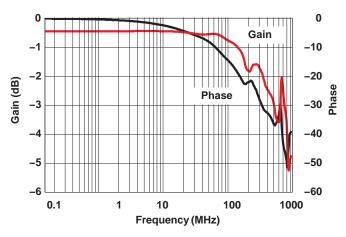
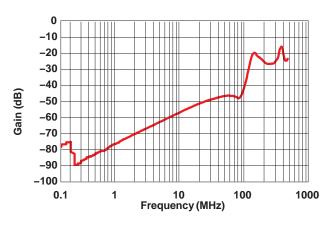


Figure 9. Bandwidth $(V_+ = 5 V)$

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TYPICAL PERFORMANCE (continued)



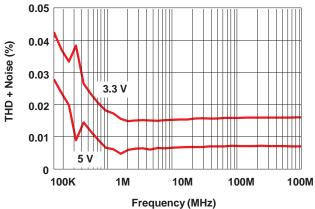


Figure 10. OFF Isolation $(V_+ = 5 V)$

Figure 11. Total Harmonic Distortion vs Frequency

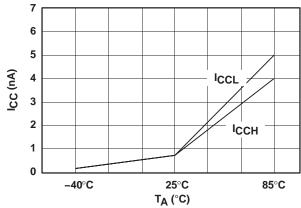


Figure 12. Power-Supply Current vs Temperature $(V_+ = 5 V)$

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PIN DESCRIPTION

PIN NUMBER	NAME	DESCRIPTION				
1	COM	Common				
2	EN	Chip enable (active low)				
3	GND	Digital ground				
4	GND	Digital ground				
5	IN	Digital control to connect COM to NC or NO				
6	NO	Normally open				
7	NC	Normally closed				
8	٧+	Power supply				

PARAMETER DESCRIPTION

SYMBOL	DESCRIPTION
VCOM	Voltage at COM
V _{NC}	Voltage at NC
V _{NO}	Voltage at NO
r _{on}	Resistance between COM and NC or COM and NO ports when the channel is ON
Δr_{on}	Difference of r _{On} between channels in a specific device
ron(flat)	Difference between the maximum and minimum value of ron in a channel over the specified range of conditions
I _{NC} (OFF)	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state
INO(OFF)	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state
INC(ON)	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state and the output (COM) open
I _{NO(ON)}	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open
ICOM(OFF)	Leakage current measured at the COM port, with the corresponding channel (COM to NO or COM to NC) in the OFF state and the output (NC or NO) open
ICOM(ON)	Leakage current measured at the COM port, with the corresponding channel (COM to NO or COM to NC) in the ON state and the output (NC or NO) open
VIH	Minimum input voltage for logic high for the control input (IN, EN)
V _{IL}	Maximum input voltage for logic low for the control input (IN, EN)
VI	Voltage at the control input (IN, EN)
I _{IH} , I _{IL}	Leakage current measured at the control input (IN, EN)
tON	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, NC, or NO) signal when the switch is turning ON.
^t OFF	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, NC, or NO) signal when the switch is turning OFF.
Q _C	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NC, NO, or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$, C_L is the load capacitance and ΔV_{COM} is the change in analog output voltage.



$\begin{array}{c} \textbf{TS5A2053} \\ \textbf{SINGLE-CHANNEL 10-} \Omega \ \textbf{SPDT ANALOG SWITCH} \\ \textbf{WITH ENABLE} \end{array}$

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PARAMETER DESCRIPTION (continued)

SYMBOL	DESCRIPTION
C _{NC(OFF)}	Capacitance at the NC port when the corresponding channel (NC to COM) is OFF
C _{NO(OFF)}	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
C _{NC(ON)}	Capacitance at the NC port when the corresponding channel (NC to COM) is ON
C _{NO(ON)}	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
C _{COM(OFF)}	Capacitance at the COM port when the corresponding channel (COM to NC or COM to NO) is OFF
C _{COM(ON)}	Capacitance at the COM port when the corresponding channel (COM to NC or COM to NO) is ON
Cl	Capacitance of control input (IN, EN)
O _{ISO}	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NC to COM or NO to COM) in the OFF state.
XTALK	Crosstalk is a measurement of unwanted signal coupling from an ON channel to an OFF channel (NC to NO or NO to NC). This is measured in a specific frequency and in dB.
BW	Bandwidth of the switch. This is the frequency where the gain of an ON channel is -3 dB below the DC gain.
THD	Total harmonic distortion describes the signal distortion caused by the analog switch. This is defined as the ratio of root mean square (RMS) value of the second, third, and higher harmonic to the absolute magnitude of fundamental harmonic.
I ₊	Static power-supply current with the control (IN, EN) pin at V ₊ or GND



PARAMETER MEASUREMENT INFORMATION

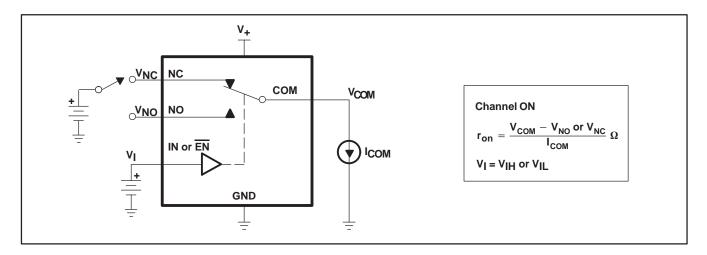


Figure 13. ON-State Resistance (ron)

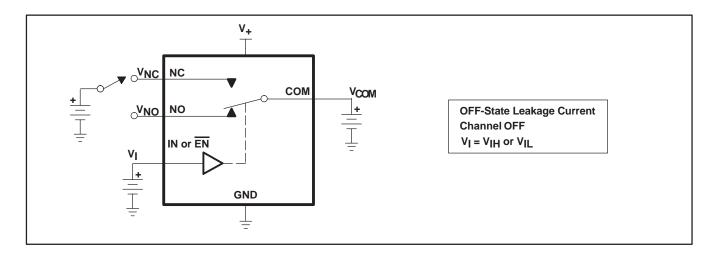


Figure 14. OFF-State Leakage Current ($I_{NC(OFF)}$, $I_{NO(OFF)}$, $I_{COM(OFF)}$)

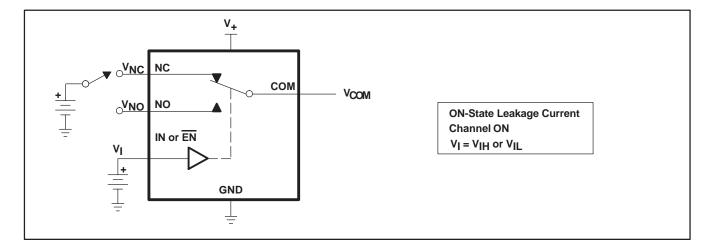
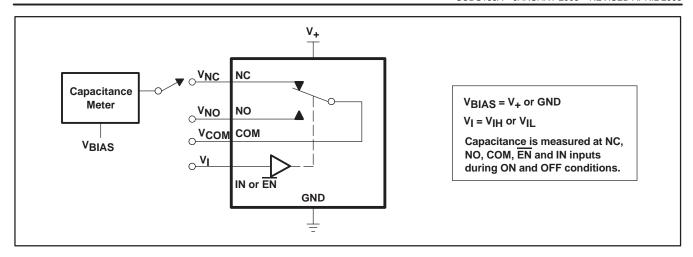
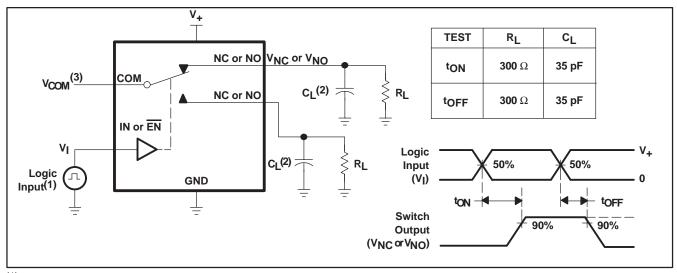


Figure 15. ON-State Leakage Current ($I_{COM(ON)}$, $I_{NC(ON)}$, $I_{NO(ON)}$)







- (1) All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f < 5 \text{ ns}$, $t_f < 5 \text{ ns}$.
- (2) C_L includes probe and jig capacitance.
- (3) See Electrical Characteristics for V_{COM}.

Figure 17. Turn-On (t_{ON}) and Turn-Off Time (t_{OFF})

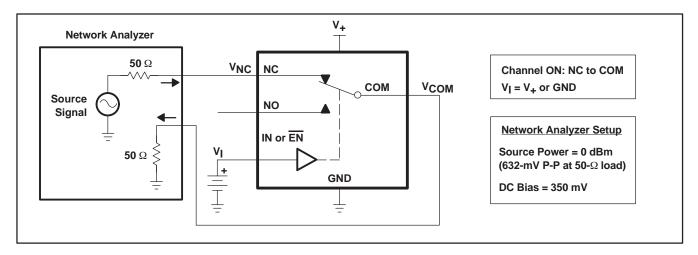


Figure 18. Bandwidth (BW)



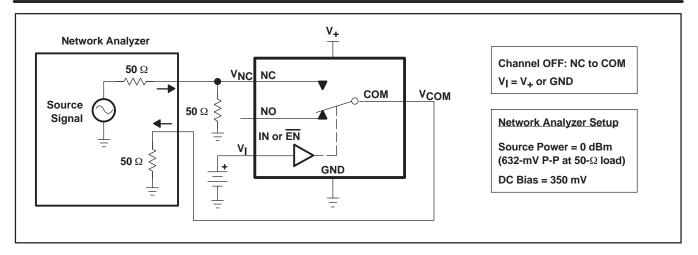


Figure 19. OFF Isolation (O_{ISO})

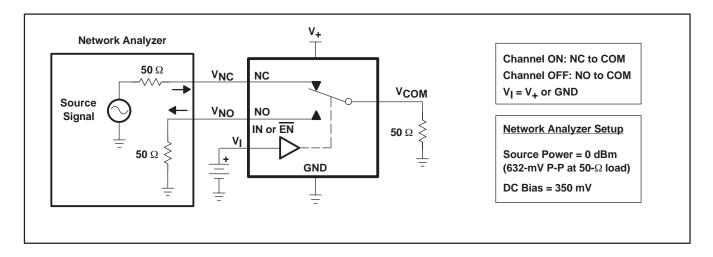
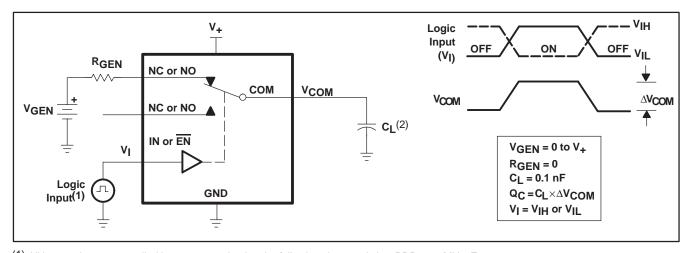


Figure 20. Crosstalk (X_{TALK})



⁽¹⁾ All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f < 5$ ns. $t_f < 5$ ns.

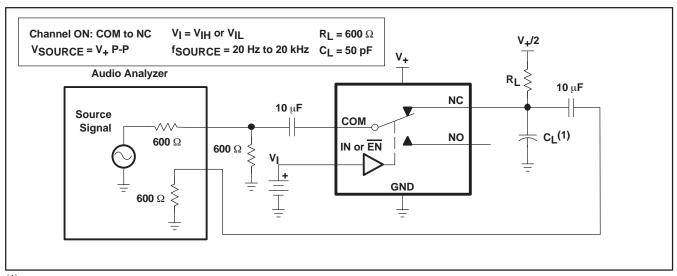
Figure 21. Charge Injection (Q_C)

⁽²⁾ C_L includes probe and jig capacitance.

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WITH ENABLE



(1) C_L includes probe and jig capacitance.

Figure 22. Total Harmonic Distortion (THD)





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TS5A2053DCTR	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	JAF Z	Samples
TS5A2053DCTRE4	ACTIVE	SM8	DCT	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	JAF Z	Samples
TS5A2053DCUR	ACTIVE	VSSOP	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	(AF ~ JAFQ ~ JAFR) JZ	Samples
TS5A2053DCURG4	ACTIVE	VSSOP	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	JAFR	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

15-Apr-2017

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS5A2053DCTR	SM8	DCT	8	3000	180.0	13.0	3.35	4.5	1.55	4.0	12.0	Q3
TS5A2053DCUR	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3
TS5A2053DCUR	VSSOP	DCU	8	3000	180.0	9.0	2.05	3.3	1.0	4.0	8.0	Q3
TS5A2053DCURG4	VSSOP	DCU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3

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*All dimensions are nominal

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS5A2053DCTR	SM8	DCT	8	3000	182.0	182.0	20.0
TS5A2053DCUR	VSSOP	DCU	8	3000	202.0	201.0	28.0
TS5A2053DCUR	VSSOP	DCU	8	3000	182.0	182.0	20.0
TS5A2053DCURG4	VSSOP	DCU	8	3000	202.0	201.0	28.0

DCT (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion
- D. Falls within JEDEC MO-187 variation DA.

DCT (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DCU (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



NOTES:

- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-187 variation CA.



DCU (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE (DIE DOWN)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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